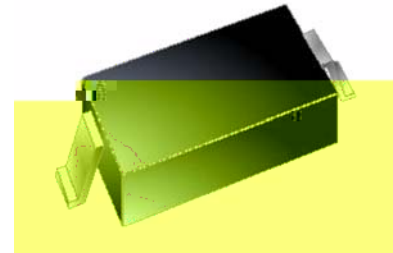


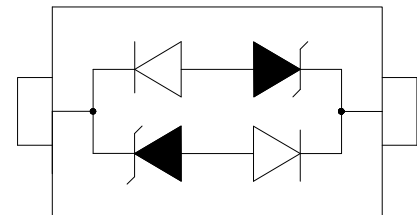


FEATURES

- 350 watts peak pulse power per line ( $t_P=8/20\mu s$ )
- Protects one bi-directional I/O line
- Low clamping voltage
- Working voltage:24V
- Low leakage current
- RoHS compliant
- AEC-Q101 qualified



SOD-323



Pin Configuration

MAIN APPLICATIONS

- Cell phone handsets and accessories
- Microprocessor based equipment
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation
- Peripherals
- USB interface

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD)  $\pm 30kV$  (air),  $\pm 30kV$  (contact)
- IEC61000-4-4 (EM M U a U a U a U a E 61000-4-4 cofi n
- Quantity per reel: 3,000pcs
- Lead finish: lead free
- Marking code: CB

**ABSOLUTE MAXIMUM RATINGS** ( $T_A=25$  , RH=45%-75%, unless otherwise noted)

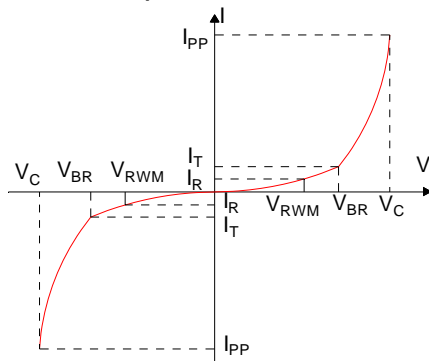
Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 8/20 $\mu$ s waveform	P <sub>PP</sub>	350	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	+/- 30 +/- 30	kV
Lead soldering temperature	T <sub>L</sub>	260 (10 sec.)	
Operating junction temperature range	T <sub>J</sub>	-55 to +150	
Storage temperature range	T <sub>STG</sub>	-55 to +150	

**ELECTRICAL CHARACTERISTICS** ( $T_A=25$  )

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V <sub>RWM</sub>				24	V
Reverse breakdown voltage	V <sub>BR</sub>	I <sub>T</sub> =1mA	26.7			V
Reverse leakage current	I <sub>R</sub>	V <sub>RWM</sub> =24V			1	$\mu$ A
Clamping voltage	V <sub>C</sub>	I <sub>PP</sub> =1A, t <sub>P</sub> =8/20 $\mu$ s			38	V
		I <sub>PP</sub> = 9A, t <sub>P</sub> =8/20 $\mu$ s			54	V
Junction capacitance	C <sub>J</sub>	V <sub>RWM</sub> =0V, f=1MHz		1.0	1.5	pF

**RATINGS AND V I CHARACTERISTICS CURVES** ( $T_A=25$  , unless otherwise noted)

**FIG.1: V- I curve characteristics (Bi-directional)**



**FIG.2: Pulse waveform (8/20 $\mu$ s)**

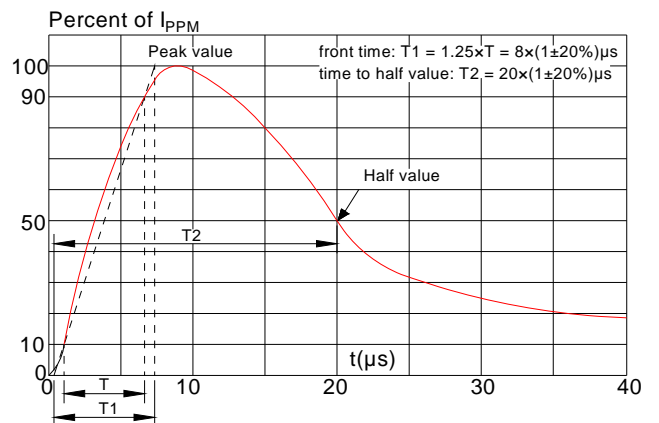


FIG.3: Pulse derating curve

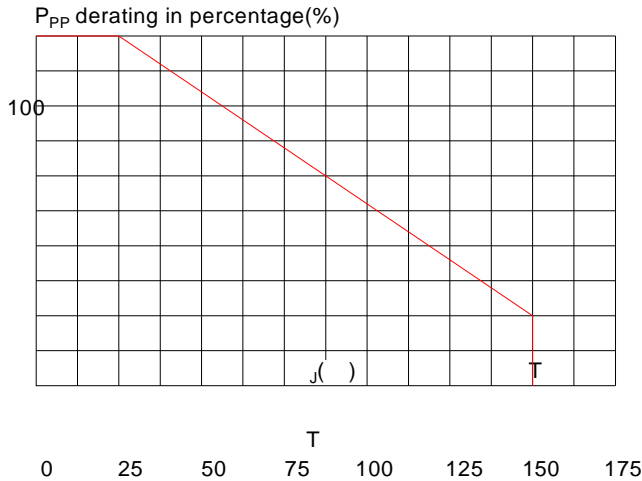
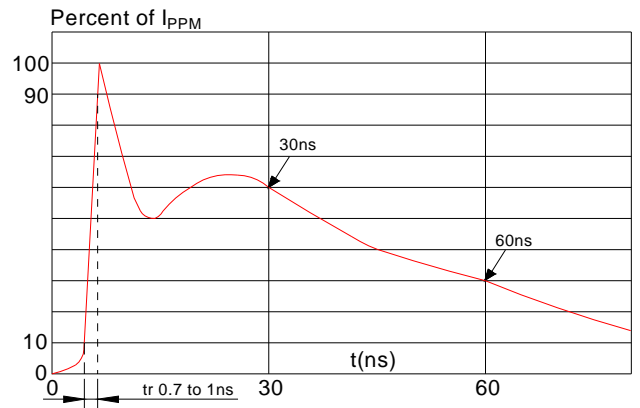
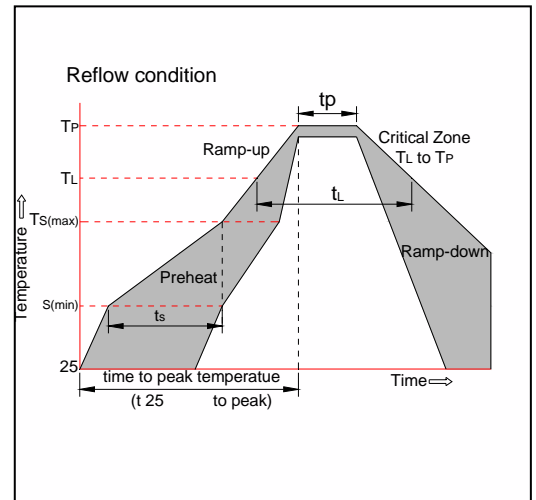


FIG.4: ESD clamping (30kV contact)

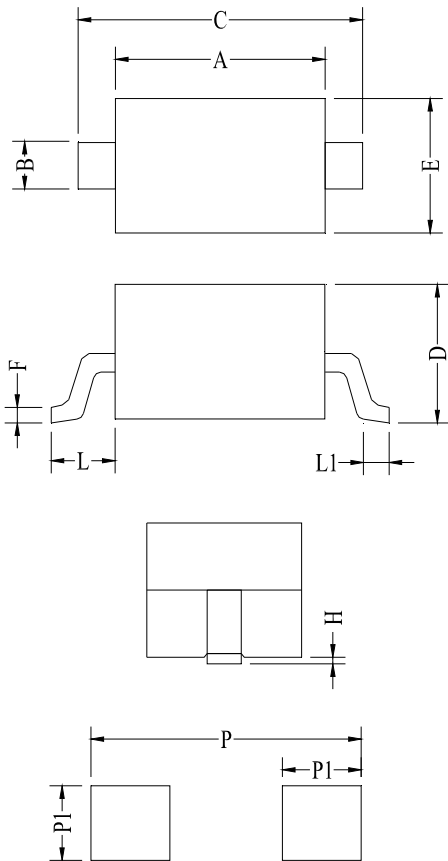


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	+150
	-Temperature Max(T <sub>s(max)</sub> )	+200
	-Time (Min to Max) (t <sub>s</sub> )	60-180 secs.
Average ramp up rate (Liquidus Temp (T <sub>L</sub> )to peak)		3 /sec. Max
T <sub>s(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T <sub>L</sub> )(Liquidus)	+217
	-Temperature(t <sub>L</sub> )	60-150 secs.
Peak Temp (T <sub>p</sub> )		+260(+0/-5)
Time within 5 of actual Peak Temp (t <sub>p</sub> )		20-4 secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T <sub>p</sub> )		8 min. Max
Do not exceed		+260



**PACKAGE MECHANICAL DATA**



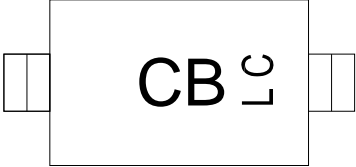
**Land Pattern**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.60	1.70	1.80	0.063	0.067	0.071
B	0.25	0.32	0.40	0.010	0.013	0.016
C	2.30	2.60	2.80	0.091	0.102	0.110
D	0.80	0.95	1.10	0.031	0.037	0.043
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.08	0.13	0.18	0.003	0.005	0.007
L	0.475REF			0.019REF		
L1	0.25	0.33	0.40	0.010	0.013	0.016
H	0.00	0.06	0.14	0.000	0.002	0.006
P	3.00			0.118		
P1	0.80			0.031		

TAPE AND REEL INFORMATION SOD 323



MARKING CODE

Part Number	Marking Code
JEB24C-AU	


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